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Dimensions

Chip Size	0603
L	1.6mm +/-0.17mm
W	0.8mm +/-0.15mm
T	0.8mm +/-0.15mm
S	0.4mm MIN
B	0.45mm +/-0.15mm

Packaging Specifications

Packaging	T&R, 180mm, Paper Tape
Packaging Quantity	4000

General Information

Series	SMD Comm X8R HT150C Flex
Style	SMD Chip
Description	SMD, MLCC, High Temperature, Ultra-Stable
Features	Ultra-Stable
RoHS	Yes
Termination	Flexible Termination
Marking	false
AEC-Q200	No
Typical Component Weight	7.3 mg
Shelf Life	78 Weeks
MSL	1

Specifications

Capacitance	4.3 pF
Measurement Condition	1 MHz 1.0Vrms
Capacitance Tolerance	+/-0.5 pF
Voltage DC	16 VDC
Dielectric Withstanding Voltage	40 VDC
Temperature Range	-55/+150°C
Temperature Coefficient	X8R
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	15%, 1MHz 1.0Vrms
Dissipation Factor	2.5% 1MHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour: Referee Time is 1000 Hours
Insulation Resistance	100 GOhms